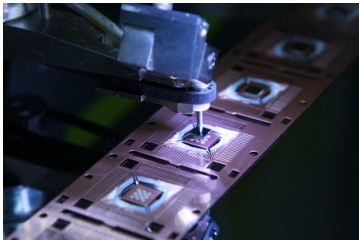


# Pressureless Silver Sintering Paste



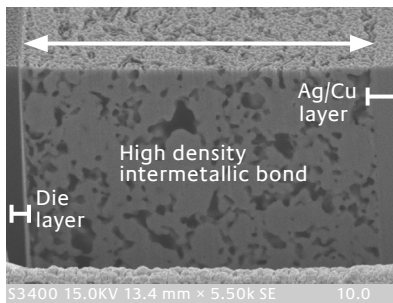
## FEATURES

- ▶ Outstanding thermal conductivity
- ▶ Outstanding electrical performance
- ▶ Pressureless sintering capability
- ▶ Outstanding interface reliability
- ▶ Outstanding workability (dispensable)
- ▶ Low temperature sintering capability

## APPLICATIONS

- ▶ High power device such as IGBT modules
- ▶ High performance LED packaging
- ▶ Alternative for high Pb solder alloys

## X-section by FIB



## General Properties

Item	Data	Appendix
Cure condition	200 deg. C 90 min.	no pressure, in air
Viscosity	140 Pa*s	E type viscometer 0.5 rpm
Elastic modulus	17.6 GPa	Tensile test
Coefficient of thermal expansion	19 ppm	TMA method
Thermal conductivity	> 200 W7m*K	Laser flash method
Volume resistance	6μ Ω	Four point probe method
Shear strength at 260 deg. C	> 30 MPa	Die backside Au/Ag plated CU LF
Applicable adhered	Ag, Au, Bare Cu	-